# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

HP EliteDesk 705 G2 SFF Business PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel
2. Remove all add-on cards
3. Remove all cables from main board and devices
4. Remove front bezel and hood lock
5. Remove SD card reader and ODD
6. Remove all equipped HDD
7. Remove PSU
8. Remove M/B
9. Remove 95W / 65W heat sink from M/B
10. Remove DDR and battery from M/B

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove access panel

1. Lift the latch to release access panel of SFF chassis as photo1 shown

2. Rotate the driver cage up to vertical position and release the retainer bracket as photo2 shown
## 2. Remove all add-on cards

<p>| | | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
</table>
| 1 |   | ![Photo3](image3)
|   |   | ![Photo4](image4)
|   |   | ![Photo5](image5)

1. Remove all of the add-on cards if SKU obtained

(See Photo3,4,5)
3. Remove all cables from main board and devices

1. Release all the cables have been connected between M/B and devices
   (See Photo6)

   1) Power cable (6 pin)
   2) Heat sink cable
   3) 12v PWR cable (4pin)
   4) Audio cable
   5) Front USBx2 & card reader
   6) HDD SATA & PWR
   7) ODD SATA & PWR
   8) Add on card cabl
   9) Hood lock cable

PSG instructions for this template are available at EL-MF877-01
4. Remove front bezel and hood lock

1. Lift up 3 latches then remove front bezel
   (See Photo7,8)

2. Release tamper proof screw then release the cable from M/B
   (6-32 x .187" Security Head)
   (See Photo9,10,11)
# 5. Remove SD card reader and ODD

<table>
<thead>
<tr>
<th>Step</th>
<th>Instruction</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Release 1 screw from card reader (6-32 x 0.187”) <em>(See Photo12)</em></td>
</tr>
<tr>
<td>2</td>
<td>Remove card reader module from chassis <em>(See Photo13,14)</em></td>
</tr>
<tr>
<td>3</td>
<td>Release the latch from ODD cage then pull ODD out of cage; direction as photo16 shown <em>(See Photo15,16)</em>&lt;br&gt;Remove the plastic latch from ODD as photo17 shown <em>(See Photo17)</em></td>
</tr>
</tbody>
</table>
6. Remove all equipped HDD

1. Lift HDD latch then press HDD to the right for escaping from cage
   *(See Photo18)*

2. Remove HDD towards up right direction as 1st HDD releasing
   *(See Photo19)*

3. Lift HDD latch (Red one) up then press HDD to the right for escaping from cage
   *(See Photo20)*
   Remove HDD towards the direction as shown as 2nd HDD releasing
   *(See Photo21)*

PSG instructions for this template are available at EL-MF877-01
1. Release the screw first then pull HDD out of cage
   (6-32 x 0.187")
   (See Photo22)

2. Remove HDD towards up right direction as 3rd HDD releasing
   (See Photo23)
7. Remove PSU

1. Release 3 screws of PSU
   (See Photo24)

2. Draw PSU to the direction as shown by pressing down the latch
   (See Photo25)

   Photo24

   Photo25

   Latch is inside here
3 Release 2 screws from PSU  
(See Photo26)

4 Release 2 screws from the other side  
(See Photo27)
5 Cut the cable tie  
(See Photo28)

6 Slide PSU cover alone the way  
(See Photo29)
7 Remove L/N from PCBA
   (See Photo30)
8 Remove fan wire from PCBA
   (See Photo31)
9  Release 3 screws of PCA
   (See Photo32)

10  Remove the capacitors
    (See Photo33)
# 8. Remove M/B

1. **Release 8 screws by order 8 to 1 to free M/B from chassis**
   
   (6-32 x 0.250”)
   
   *(See Photo34)*

2. **Follow the direction to drag M/B out of chassis**
   
   *(See Photo35)*
9. Remove 95W / 65W heat sink from M/B

<table>
<thead>
<tr>
<th>Step</th>
<th>Action</th>
</tr>
</thead>
</table>
| 1    | Release 4 screws by order 4 to 1 to free 95W heat sink from chassis  
(See Photo36) |
| 2    | Release 4 screws by order 4 to 1 to free 65W heat sink from chassis  
(See Photo37) |

PSG instructions for this template are available at [EL-MF877-01](https://www.example.com/EL-MF877-01)
10. Remove DDR and battery from M/B

1. Release DDR by flipping latches outwards as direction shown
   (See Photo38)

2. Remove battery from M/B by detaching the clip outwards as direction shown
   (See Photo39)

   Remove coin battery from MB

PSG instructions for this template are available at EL-MF877-01